PALOMAR TECHNOLOGIES
Precision Process Performance

Wedge Bonding

Deep Access, Large Area

Palomar Technologies continues to support and offer both new and factory refurbished wedge bonders.

The Model 2470-V is built on a proven platform, backed by years of rigorous production use in demanding applications worldwide. Our family of interconnection products coupled with extensive applications experience brings solutions to your challenging production requirements.

The 3470-II offers the same rich feature set as the 2470-V but has an even larger work area to accommodate large assemblies or multiple setups.

Precise loop and wire length control. High frequency impedance matching and long low loops control package inductances; provides reduction of rework and test iterations; and allows assembly of thin profile packages.

Dual-mode ultrasonics provides over 100 discrete programmable power levels for adjustment to variations in bonding surfaces, packages, and parts.

Expansive X-Y robotic positioners are capable of moving the standard 16"^{2} (4" x 4") work stage or optional 24"^{2} (4" x 6") work stage over a 60"^{2} (5"x 12") area (2470-V). The 3470-II is capable of moving to any position within a 32.5" x 19.5 " work envelope.

Large 2-in. wire spool reduces downtime for spool changeover, or an optional de-spooler controls wire tension by automatically feeding wire on demand to the bond head.

Mega-program capability allows data storage for positioning and forming up to 8000 wires in a single program.

Host Data Option provides a software link to a factory's external central CIM computer.

On-screen menus prompt operators through the setup, programming, and operation processes.

2470-V